

Title (en)

Method for defining a punching tool set for punching of work pieces and punching machine with such a punching tool set

Title (de)

Bearbeitungsprogramm zum Betreiben einer Stanzmaschine zum stanzenden Bearbeiten von Werkstücken, insbesondere von Blechen

Title (fr)

Procédé de définition d'un ensemble d'outil de poinçonnage destiné au traitement par poinçonnage de pièces usinées ainsi que machine de poinçonnage dotée d'un tel ensemble d'outil de poinçonnage

Publication

**EP 2522443 A3 20121205 (DE)**

Application

**EP 12179637 A 20081018**

Priority

- EP 12179637 A 20081018
- EP 08018279 A 20081018

Abstract (en)

[origin: EP2177290A1] The method involves removing material from a reprocessed die (16) and changing a location of a cutting edge of the die to a punch entry direction. A punch and a metal sheet thickness are assigned to the reprocessed die based on the change in the cutting edge cross-section of the reprocessed die. Independent claims are included for the following: (1) reprocessed die; (2) punch machine; and (3) computer readable medium storing program for reprocessing die.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

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- [YA] JP H10277662 A 19981020 - HITACHI CABLE
- [YA] DE 102006049044 A1 20080424 - TRUMPF WERKZEUGMASCHINEN GMBH [DE]
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- [A] JP 2007007703 A 20070118 - PUNCH INDUSTRY CO LTD

Designated contracting state (EPC)

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DOCDB simple family (publication)

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DOCDB simple family (application)

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